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					Label Table
				Variant	Label Text
				001	ChangeMe!
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	ZZ2				
	Assemb These ass	oly Note semblies are ESD sensitive	ESD precautions s	hall be observed.	
	ZZ3	bly Note			e of no clean flux is not acceptable.
	ZZ4				
	These ass	oly Note semblies must comply with v	workmanship standa	ards IPC-A-610 Clas	ss 2, unless otherwise specified.

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			TID #: 00645				
			Number: TIDA-00645 Rev: E1				
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licensors do not warrant that the design	n is production worthy. You should completely validate and test your des	sign implementation to confirm the system functionality for your application	on. Engineer: Philip Beard				
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